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## (54) RESIN COMPOSITION, FILM THEREOF, AND CURED PRODUCT THEREOF

## (57) Abstract:

PROBLEM TO BE SOLVED: To provide a resin composition used for, e.g. a resistor pattern which can be developed with water or an aqueous alkali solution, having good precision, leaves little organic residues when baked by heating, and having excellent adhesion, a film thereof, and a cured product thereof.

SOLUTION: This composition contains a polymer (A) obtained by reacting a polymer prepared from a compound (a) having one (meth)acryloyl or vinyl group

and one glycidyl group in the molecule and an ethylenically unsaturated monomer copolymerizable with the compound (a) with an oligo- or poly-ethylene glycol (d) having an amino group at one terminal thereof and a compound (e) having one (meth)acryloyl or vinyl group and one carboxyl group in the molecule or a compound (A') obtained by allowing polymer A to enter into an addition reaction with a polycarboxylic anhydride, a diluent, a photopolymerization initiator, and at least one member selected among metal powder, metal oxides and glass.

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